

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0736590002](#)  
**Status:** **Active**  
**Overview:** [hdm](#)  
**Description:** 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm (30µ")

**Documents:**

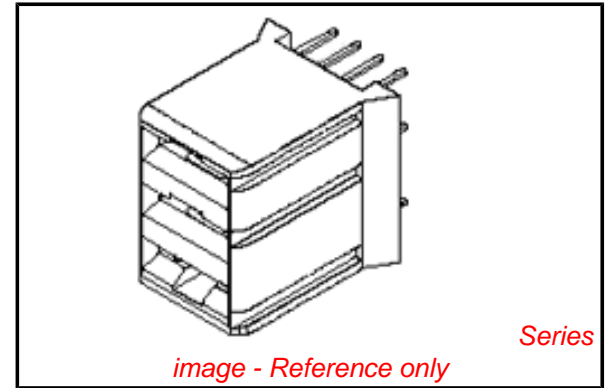
[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Drawing \(PDF\)](#)

**General**

Product Family	Backplane Connectors
Series	<a href="#">73659</a>
Application	Backplane
Comments	Midplane Power Module
Component Type	Power Header
Overview	<a href="#">hdm</a>
Product Name	HDM®
Style	N/A

**Physical**

Circuits (Loaded)	12
Circuits (maximum)	12
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.098 In
PC Tail Length (mm)	2.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	150
Plating min: Termination (µm)	3.75
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole



**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC  
Contains SVHC: No**  
**Halogen-Free  
Status**

**China RoHS**



**Not Reviewed**

**Need more information on product  
environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73659Series](#)

**Mates With**

[73651](#) HDM® Board-to-Board  
 Daughterboard Power Module

**Electrical**

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

**Solder Process Data**

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

**Material Info****Reference - Drawing Numbers**

Packaging Specification	PK-70873-0819
Sales Drawing	SDA-73659-000*

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This document was generated on 05/14/2010

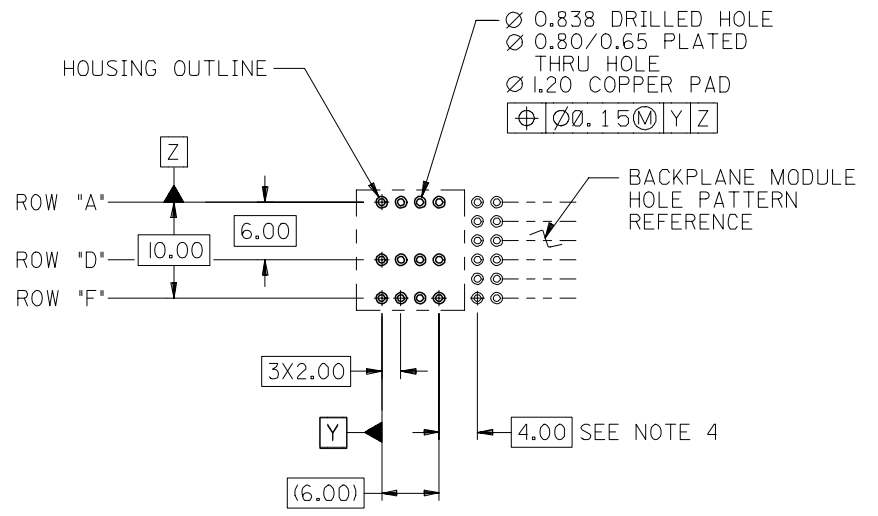
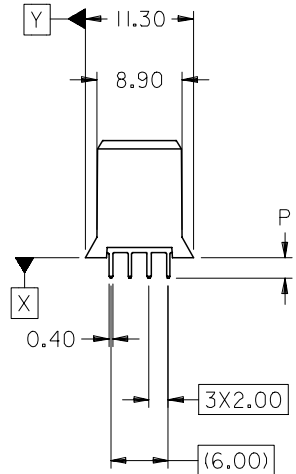
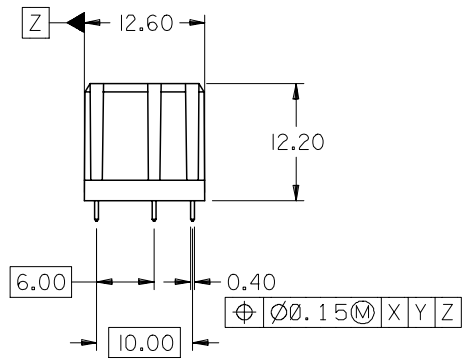
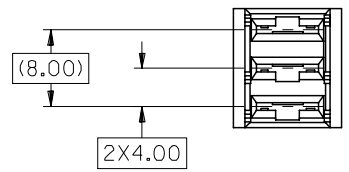
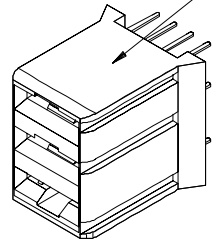
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MATERIAL NUMBER	DIM "P" ±0.25
73659-0001	2.00
73659-0002	2.50
73659-0003	3.00
73659-0004	3.50

DATE CODE AND PART NUMBER ON THIS SURFACE OR SURFACE OPPOSITE.

NOTES:

- MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK  
TERMINAL - BERYLLIUM COPPER
- FINISH:  
0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA  
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA  
NICKEL (Ni) UNDERPLATE OVERALL.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
- THIS DIMENSION MUST BE A MULTIPLE OF 4.00mm.
- DIMENSION ARE IN MILLIMETERS.



PCB LAYOUT: COMPONENT SIDE  
RECOMMENDED PCB THICKNESS: 1.57 MIN

MODIFY FINISH EC NO: UCP2007-2259 DRWN:MSI/BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	▽=0 ▽=0	<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.10</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table> ANGULAR ±1/2°		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.10	± ---	1 PLACE	± 0.25	± ---	MM ONLY	2:1	METRIC	
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DRAWN BY: REED CHECKED BY: BINGHAM APPROVED BY: BIXLER	DATE: 1996/12/10 DATE: 1996/12/10 DATE: 1996/12/10	TITLE	SALES ASSY HDM BACKPLANE POWER MODULE WITH SOLDER TAILS																		
MATERIAL NO. SEE TABLE	DOCUMENT NO. SDA-73659-000*	MOLEX INCORPORATED SHEET NO. 1 OF 1																			

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

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